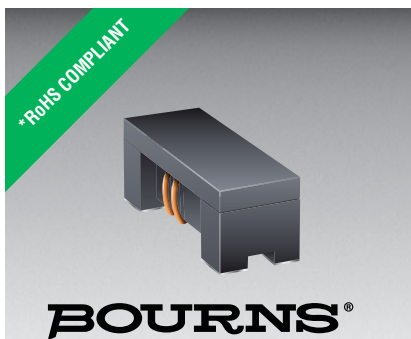




Features

- High impedance value
- Current rating up to 400 mA
- RoHS compliant* and halogen free**

Applications

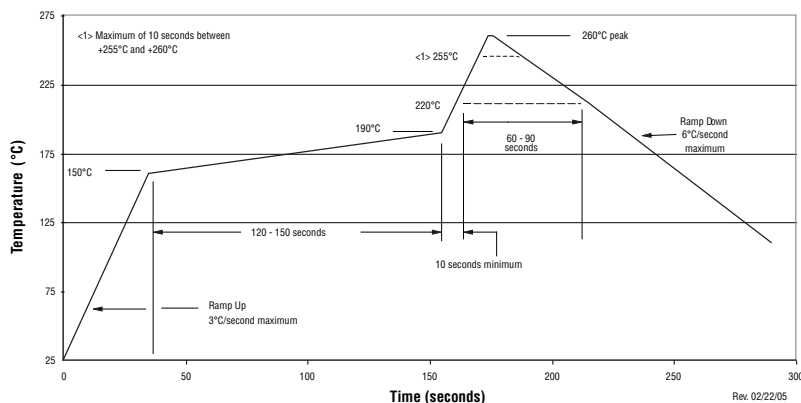
- Noise suppression
- Personal computers
- Display panels

SRF2012A Series - Common Mode Chip Inductors

Electrical Specifications

Part Number	Impedance @ 100 MHz		Rated Voltage (VDC)	Withstanding Voltage (DC)	Insulation Resistance (MΩ) Min.	DCR Max. (Ω)	IDC Max. (mA)
	(Ω)	Tolerance (%)					
SRF2012-300YA	30	±25	50	125	10	0.20	400
SRF2012-670YA	67	±25	50	125	10	0.25	400
SRF2012-900YA	90	±25	50	125	10	0.30	400
SRF2012-121YA	120	±25	50	125	10	0.30	400
SRF2012-161YA	160	±25	50	125	10	0.35	350
SRF2012-181YA	180	±25	50	125	10	0.35	350
SRF2012-201YA	200	±25	50	125	10	0.40	300
SRF2012-221YA	220	±25	50	125	10	0.40	300
SRF2012-261YA	260	±25	50	125	10	0.40	300
SRF2012-301YA	300	±25	50	125	10	0.50	300
SRF2012-361YA	360	±25	50	125	10	0.50	300
SRF2012-371YA	370	±25	50	125	10	0.50	300
SRF2012-501YA	500	±25	50	125	10	0.50	300
SRF2012-671YA	670	±25	50	125	10	0.60	140
SRF2012-901YA	900	±25	50	125	10	0.88	100

Soldering Profile

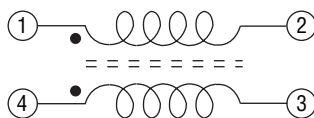


How to Order

SRF2012 - 201 Y A

Model _____
Value Code (see table) _____
Tolerance Code _____
Model Suffix _____

Schematic



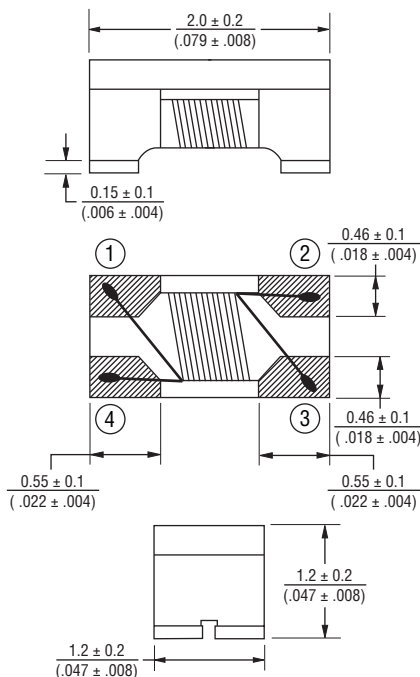
General Specifications

Reflow soldering 230 °C; 50 sec max.
Operating Temperature
.....-55 °C to +125 °C
(Temperature rise included)
Storage Temperature
.....-55 °C to +125 °C
Resistance to Soldering Heat
..... 260 °C, 10 sec. max.
Temperature Rise30 °C max. at IDC

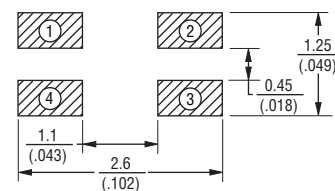
Materials

Core.....Ferrite
Wire.....Enameled copper
Terminal.....Ag/Ni/Sn
Packaging..... 2000 pcs. per 7-inch reel

Product Dimensions



Recommended Layout



DIMENSIONS: $\frac{\text{MM}}{\text{(INCHES)}}$

* RoHS Directive 2002/95/EC Jan. 27, 2003 including annex and RoHS Recast 2011/65/EU June 8, 2011.

** Bourns considers a product to be "halogen free" if (a) the Bromine (Br) content is 900 ppm or less;

(b) the Chlorine (Cl) content is 900 ppm or less; and (c) the total Bromine (Br) and Chlorine (Cl) content is 1500 ppm or less.

Specifications are subject to change without notice.

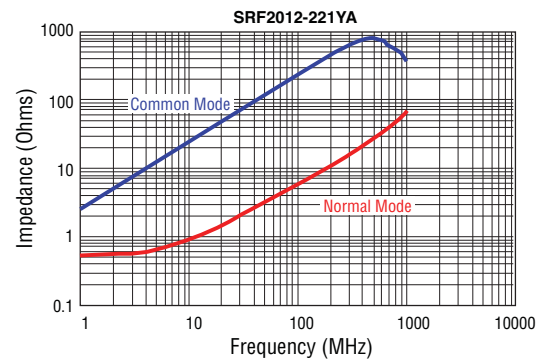
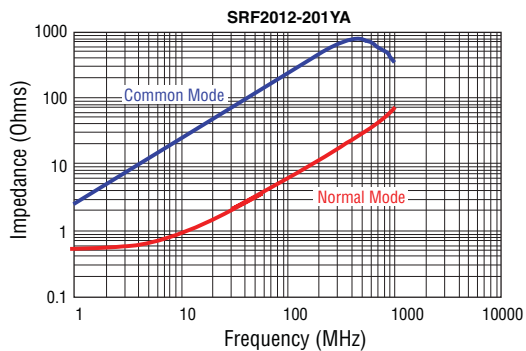
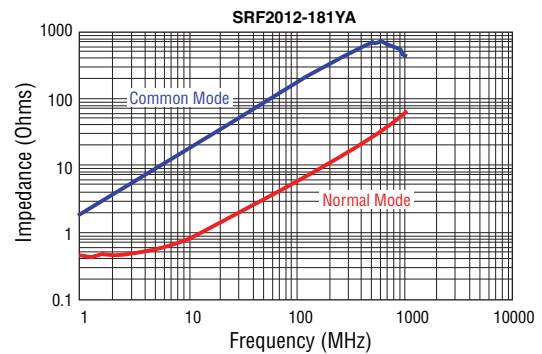
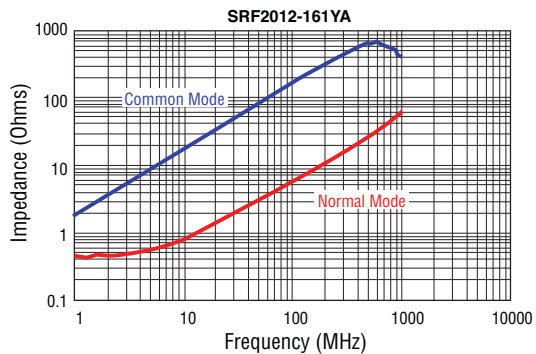
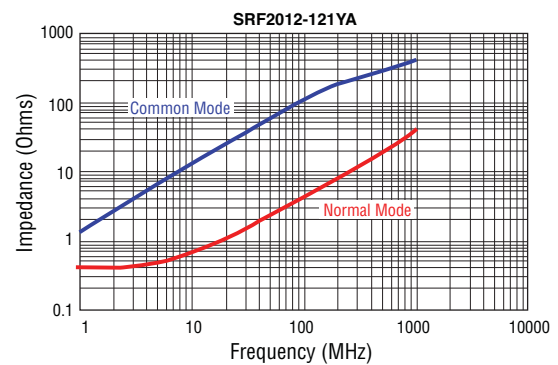
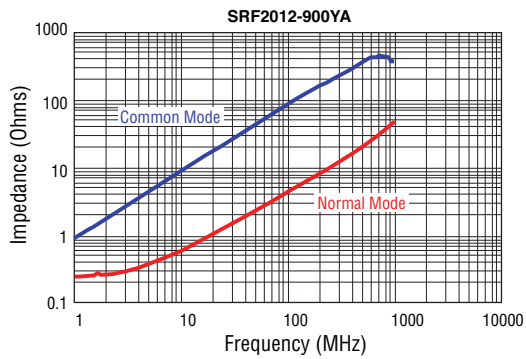
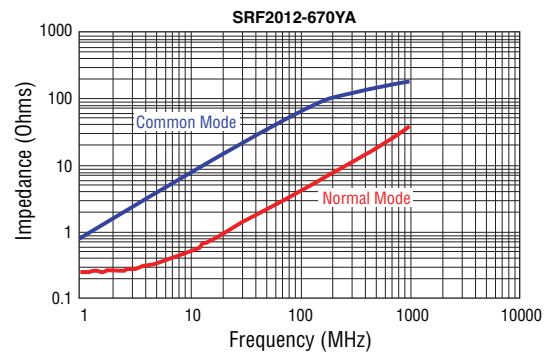
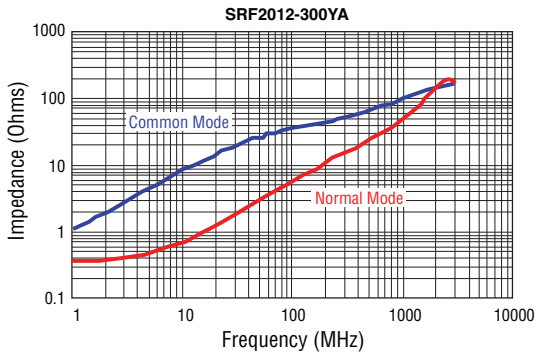
The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time.

Users should verify actual device performance in their specific applications.

SRF2012A Series - Common Mode Chip Inductors

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Typical Impedance vs. Frequency Curves

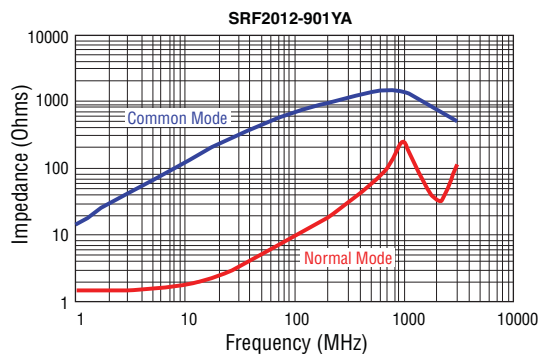
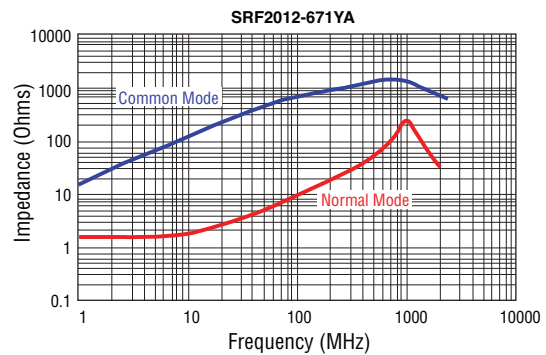
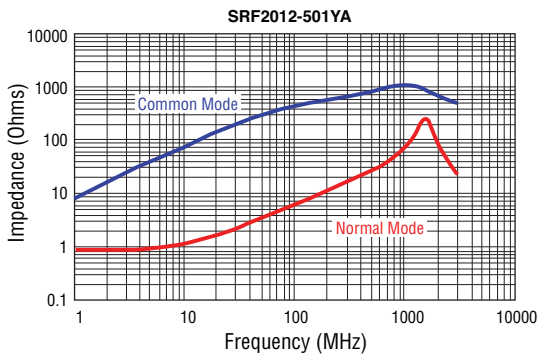
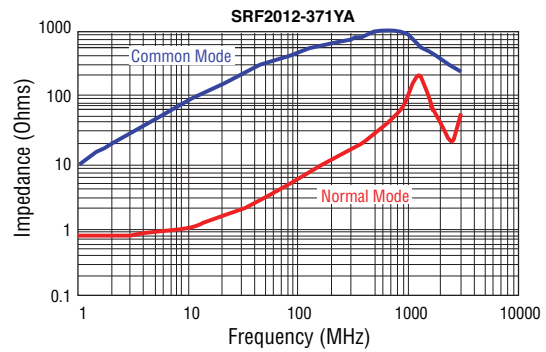
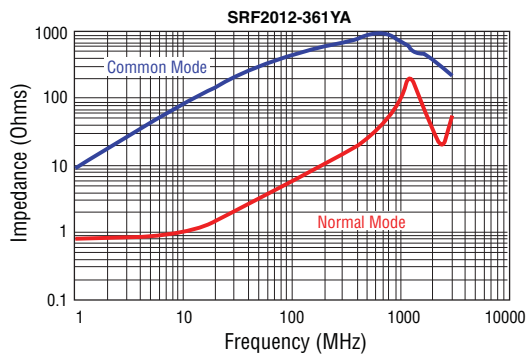
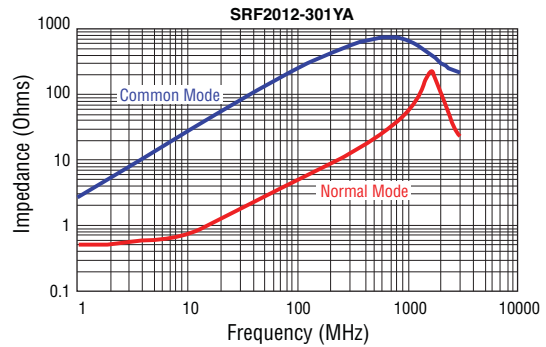
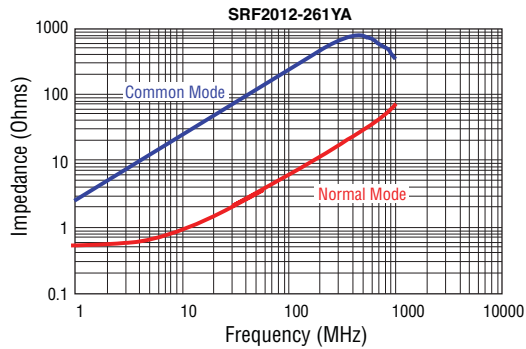


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SRF2012A Series - Common Mode Chip Inductors

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Typical Impedance vs. Frequency Curves (Continued)

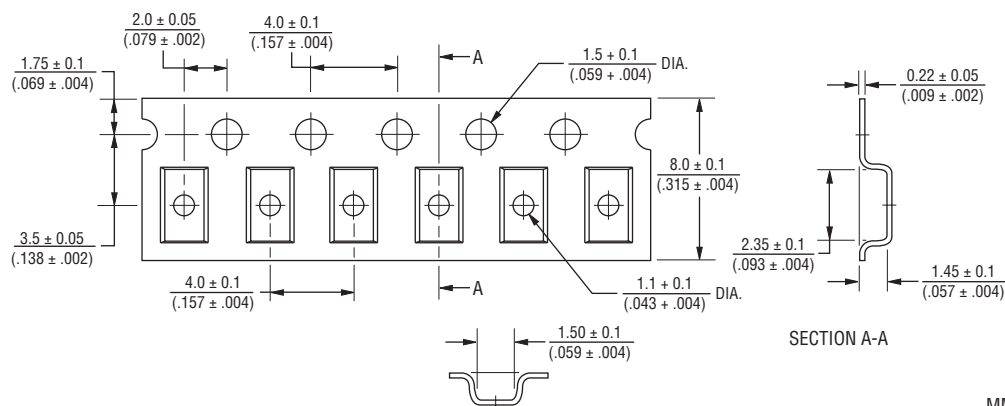
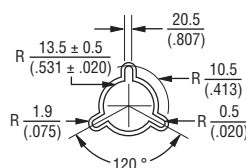
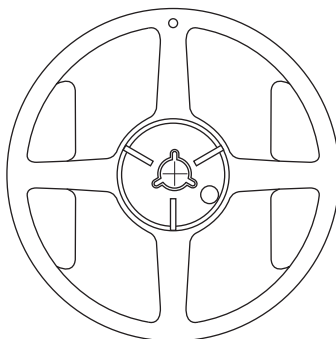


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The device characteristics and parameters in this data sheet can and do vary in different applications and actual device performance may vary over time. Users should verify actual device performance in their specific applications.

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Figure 1 shows a technical drawing of a vertical shaft. The shaft has a central section with a diameter of 13.5 ± 0.5 ($.531 \pm .020$) DIA. Above this section is a wider section with a diameter of 9.0 ± 0.5 ($.354 \pm .020$). Below the central section is another wider section with a diameter of 178 ± 2 ($7.008 \pm .079$). The total length of the shaft is 60 ± 2 ($2.362 \pm .079$).



SECTION A-A

DIMENSIONS: $\frac{\text{MM}}{(\text{INCHES})}$

USER DIRECTION OF FEED
QTY: 2000 PCS. PER REEL

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